

BG17C

5-6000 MHz Cascadable InGaP HBT Gain Block



Device Features

- OIP3 = 30 dBm @ 1900 MHz
- Gain = 16.4 dB @ 1900 MHz
- Output P1 dB = 17 dBm @ 1900 MHz
- 50 Ω Cascadable
- Patented temperature compensation
- Lead-free/RoHS-compliant SOT-89 SMT package



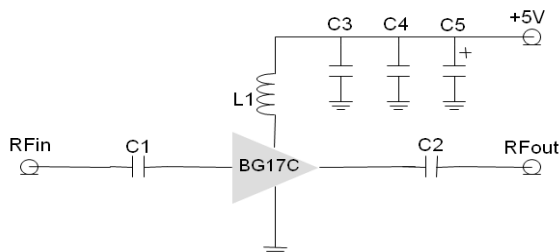
Product Description

BeRex's BG17C is a high performance InGaP/ GaAs HBT MMIC amplifier, internally matched to 50 Ohms and uses a patented **temperature compensation** circuit to provide stable current over the operating temperature range without the need for external components. The BG17C is designed for high linearity gain block applications that require high gain and low power consumption at 5V. It is packaged in a RoHS-compliant with SOT-89 surface mount package.

Applications

- Base station Infrastructure/RFID
- Commercial/Industrial/Military wireless system

Applications Circuit



*C1, C2, C3 = 100 pF $\pm$ 5%; C4 = 1000 pF $\pm$ 5%; C5 = 10 μ F; L1 = 33 nH

*less than 20 nH improves RF performance at over 1.9 GHz.

*40 nH or higher value L1 improves RF performance at under 500 MHz.

*Optimum value of L1 may vary with board design.

Typical Performance¹

Parameter	Frequency						Unit
	500	900	1900	2140	2450	5800	MHz
Gain	18.0	17.8	16.4	16.0	15.6	11.0	dB
S11	-15.0	-14.0	-24.0	-16.0	-14.0	-11.4	dB
S22	-14.0	-22.0	-12.0	-11.0	-10.0	-8.0	dB
OIP3 ²	31.0	31.0	30.0	30.0	29.0	24.5	dBm
P1dB	17.1	17.5	17.0	17.0	16.1	12.3	dBm
NF	3.8	3.9	4.0	4.0	4.0	6.6	dB

¹ Device performance _ measured on a BeRex evaluation board at 25°C, 50 Ω system.

² OIP3 _ measured with two tones at an output of 2 dBm per tone separated by 1 MHz.

	Min.	Typical	Max.	Unit
Bandwidth	5		6000	MHz
I _C @ (V _C = 5V)	45	55	65	mA
V _C		5.0		V
dG/dT		-0.004		dB/°C
R _{TH}		50		°C/W

Absolute Maximum Ratings

Parameter	Rating	Unit
Operating Case Temperature	-40 to +85	°C
Storage Temperature	-55 to +155	°C
Junction Temperature	+220	°C
Operating Voltage	+6.5	V
Supply Current	150	mA
Input RF Power	23	dBm

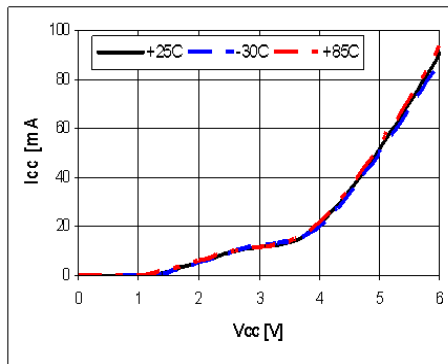
Operation of this device above any of these parameters may result in permanent damage.

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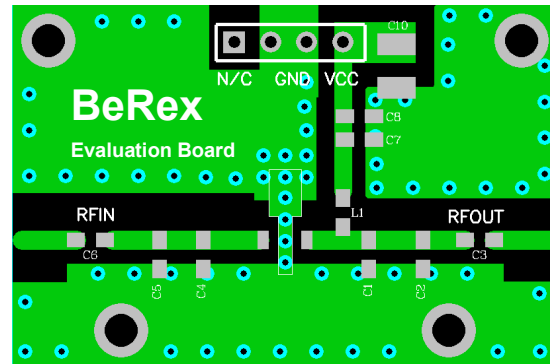
5-6000 MHz Cascadable InGaP HBT Gain Block



V-I Characteristics

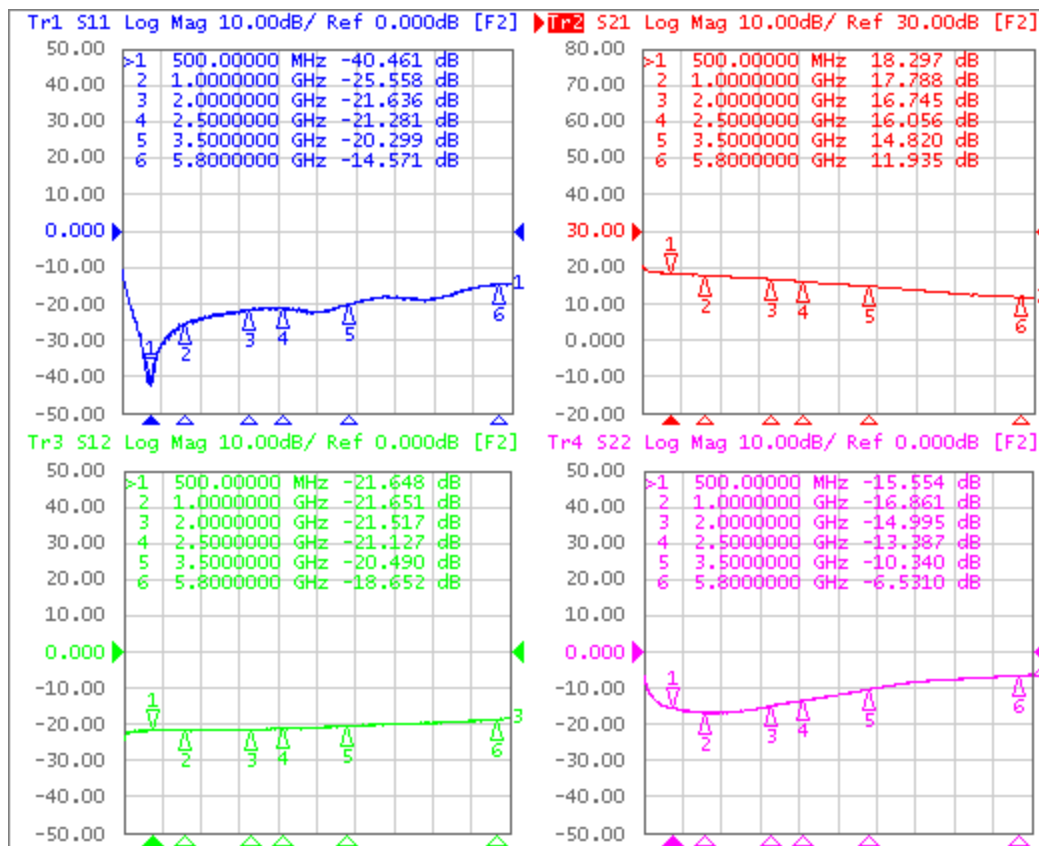


BeRex SOT89 Evaluation Board



*Dielectric constant _ 4.2 *RF pattern width 52mil *31mil thick FR4 PCB

Typical Device Data



S-Parameter

(V_{device} = 5.0V, I_{cc} = 55mA, T = 25 °C, calibrated to device leads)

Freq [MHz]	S11 [Mag]	S11 [Ang]	S21 [Mag]	S21 [Ang]	S12 [Mag]	S12 [Ang]	S22 [Mag]	S22 [Ang]
100	0.18	-61.72	9.39	165.12	0.07	14.00	0.33	-39.57
500	0.01	10.57	8.24	154.56	0.08	1.06	0.17	-40.39
1000	0.05	51.39	7.76	134.93	0.08	-1.88	0.14	-62.54
1500	0.07	24.78	7.29	115.38	0.08	-4.63	0.15	-89.81
2000	0.08	0.55	6.87	96.16	0.08	-7.41	0.18	-112.95
2500	0.09	-8.04	6.35	77.48	0.09	-9.20	0.22	-134.94
3000	0.08	14.14	5.88	60.67	0.09	-12.34	0.25	-157.37
3500	0.10	50.14	5.51	43.30	0.09	-15.00	0.31	179.17
4000	0.12	73.79	5.05	27.13	0.10	-19.42	0.36	161.72
6000	0.18	155.53	3.82	-32.99	0.12	-43.40	0.48	152.34

Typical Performance (V_d = 5V, I_c = 55mA, T = 25°C)

Freq	MHz	500	900	1900	2140	2450	3000	3500	5800
S21	dB	18.0	17.8	16.4	16.0	15.6	15.0	14.9	11.0
S11	dB	-15.0	-14.0	-24.0	-16.0	-14.0	-11.0	-20	-11.4
S22	dB	-14.0	-22.0	-12.0	-11.0	-10.0	-9.0	-12.1	-8.0
P1	dBm	17.1	17.5	17.0	17.0	16.1	15.2	15	24.5
OIP3	dBm	31.0	31.0	30.0	30.0	29.0	28.0	27.5	12.3
NF	dB	3.8	3.9	4.0	4.0	4.0	4.2	4.2	6.6

Typical Performance (V_d = 4.7V, I_c = 43mA, T = 25°C)

Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	20.0	18.0	17.6	16.0	15.8	15.5	14.7
S11	dB	-13	-20.2	-24	-15.3	-14.6	-16.7	-18.9
S22	dB	-5.9	-10.9	-14.7	-10.4	-10.1	-11.2	-11.9
P1	dBm	13.9	14.4	14.9	14.2	13.9	14.6	14.0
OIP3	dBm	28.5	26	27.5	27.5	26.5	27	26
NF	dB	3.8	3.8	3.9	4.0	4.0	4.0	4.2

Typical Performance (V_d = 4.5V, I_c = 37mA, T = 25°C)

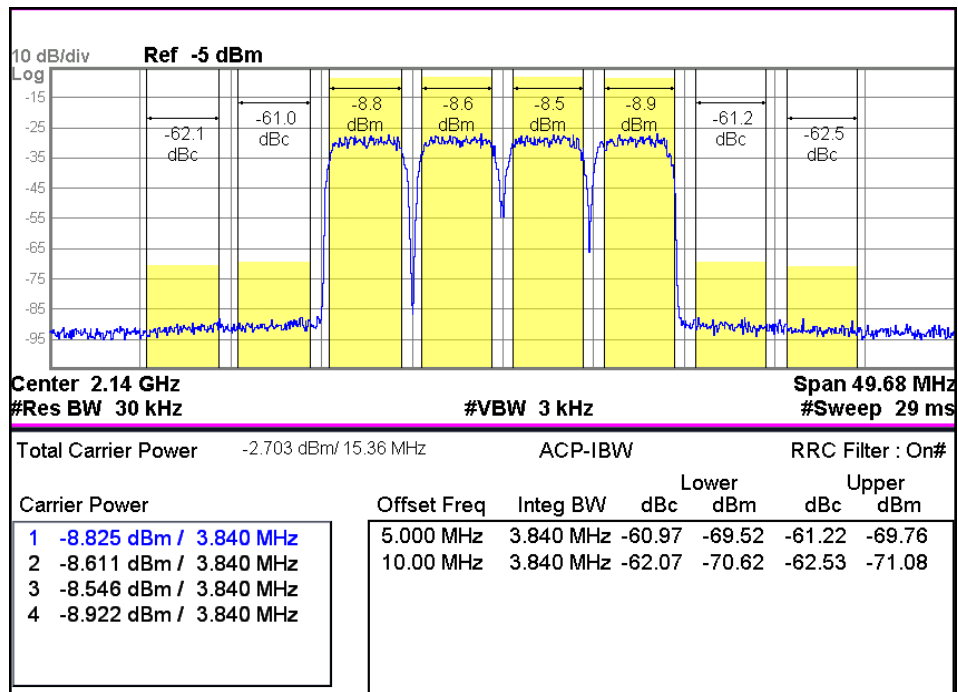
Freq	MHz	70	500	900	1900	2140	2450	3500
S21	dB	19.5	17.8	17.4	15.9	15.7	15.3	14.6
S11	dB	-12.5	-18.7	-21.7	-14.7	-14.1	-16.1	-18
S22	dB	-5.8	-10.5	-13.9	-10.1	-9.7	-10.9	-11.6
P1	dBm	13.6	14.3	14.3	13.7	13.2	12.7	12.5
OIP3	dBm	27.5	27.0	24.5	24.5	24	24.0	23.5
NF	dB	3.8	3.8	3.9	4.0	4.0	4.0	4.2

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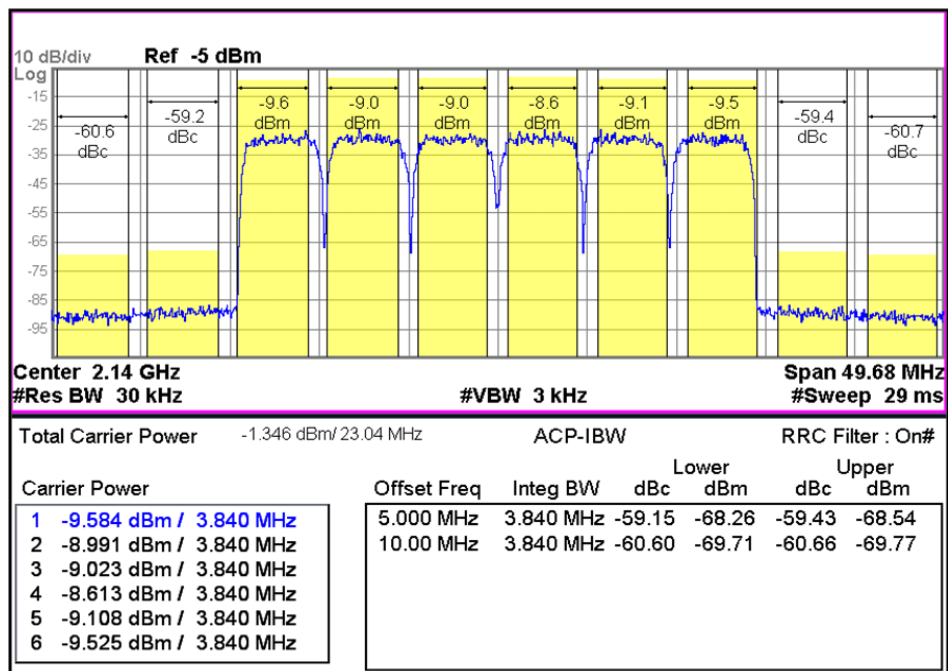
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WCDMA 4FA 2140 -60dBc



WCDMA 6FA 2140 -60dBc

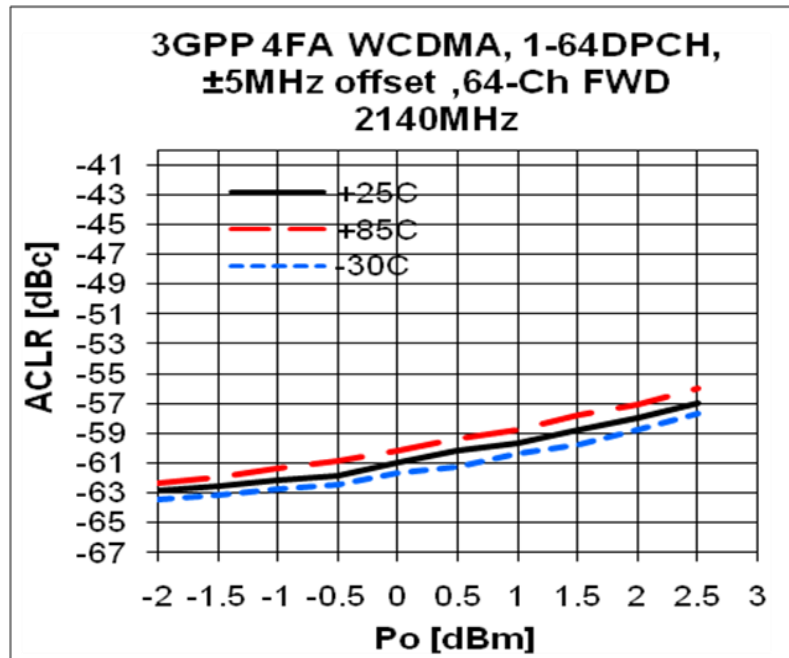


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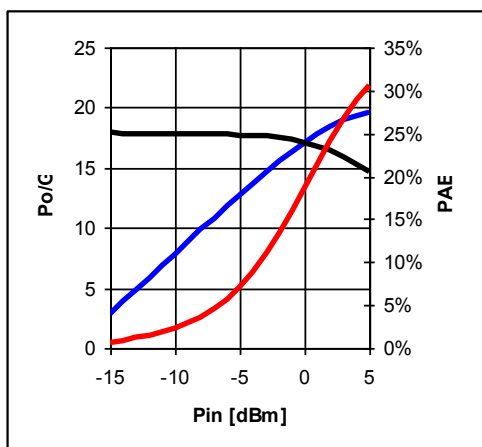


ACLR

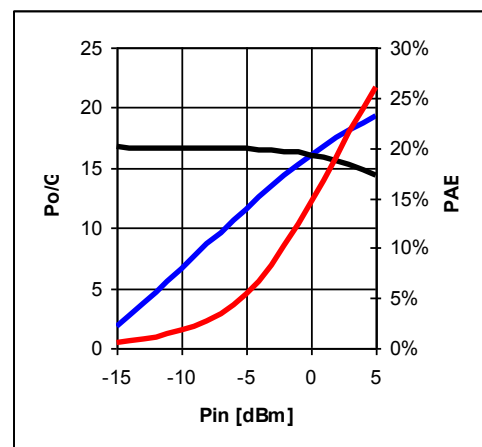


Device Performance

Pin-Pout-Gain



900MHz, 5V/55mA



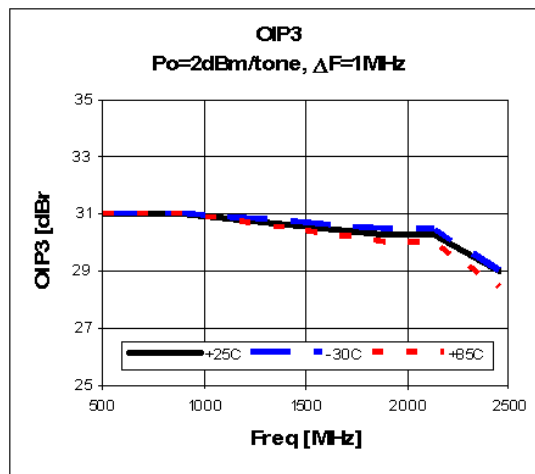
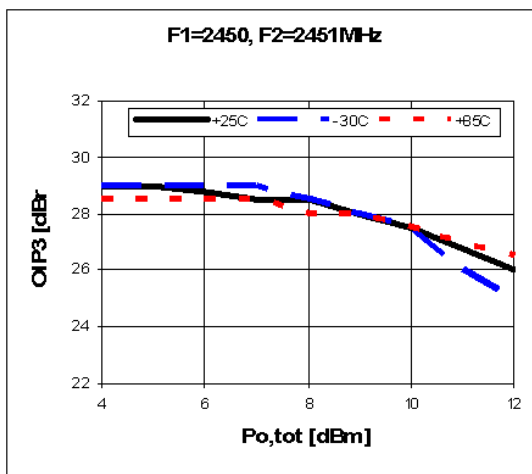
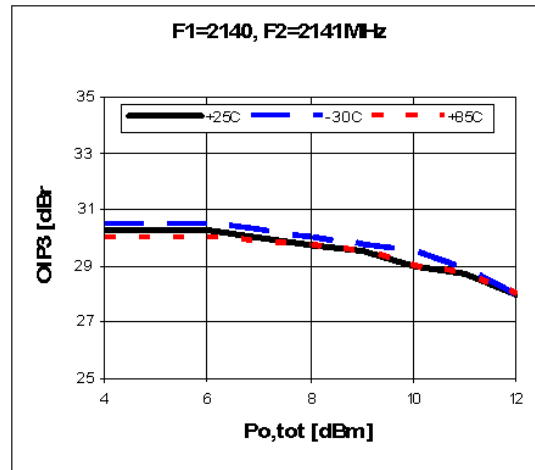
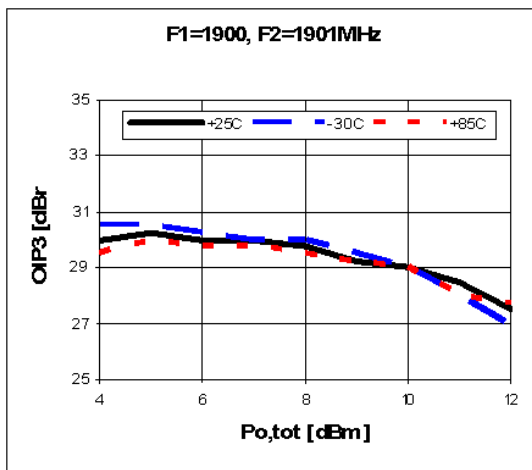
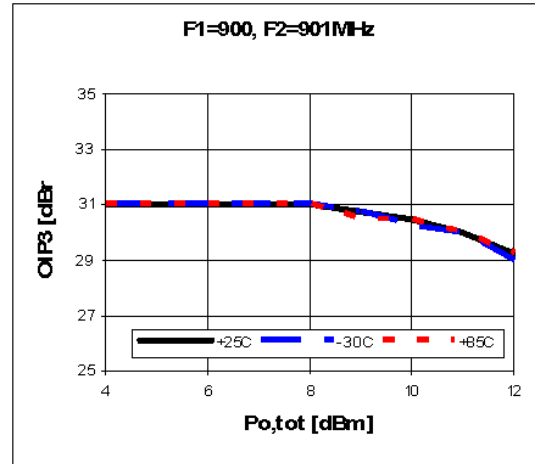
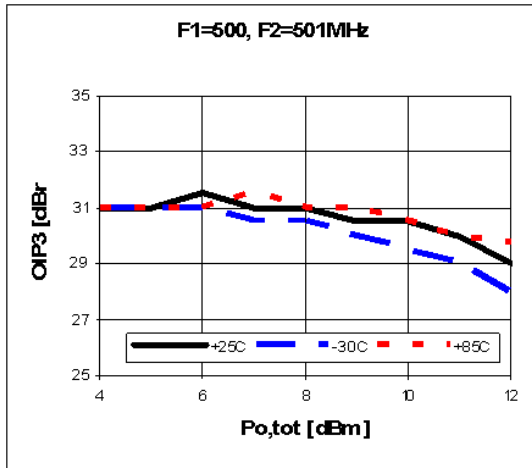
1900 MHz, 5V/55mA

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OIP3

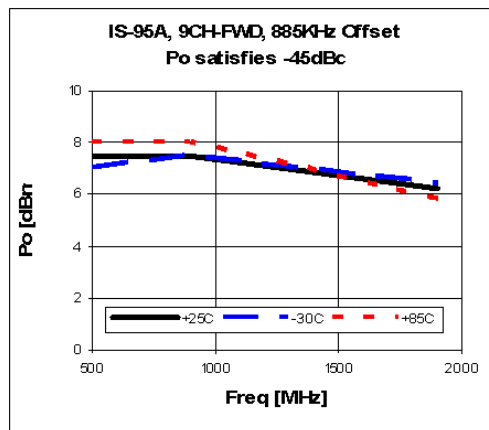
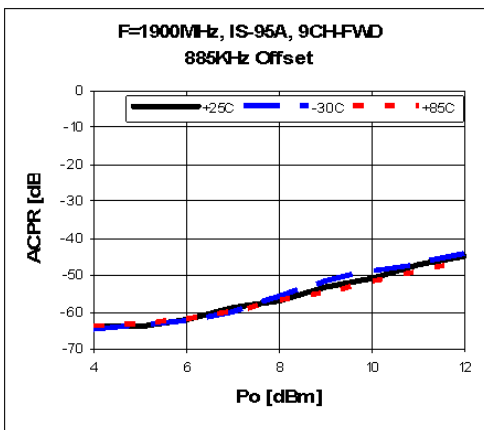
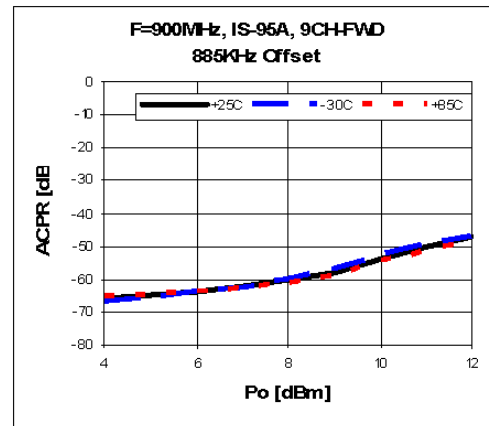
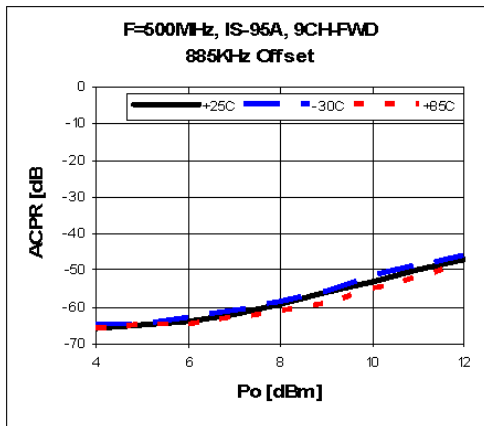


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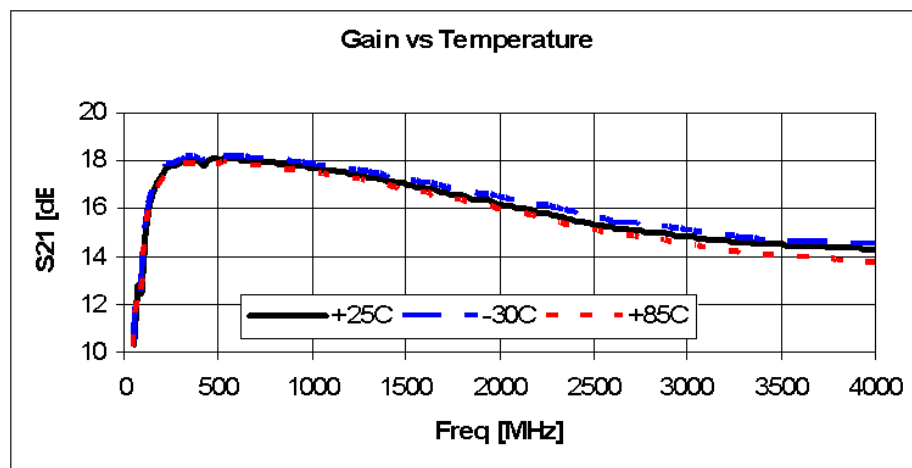
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ACPR



Gain Flatness

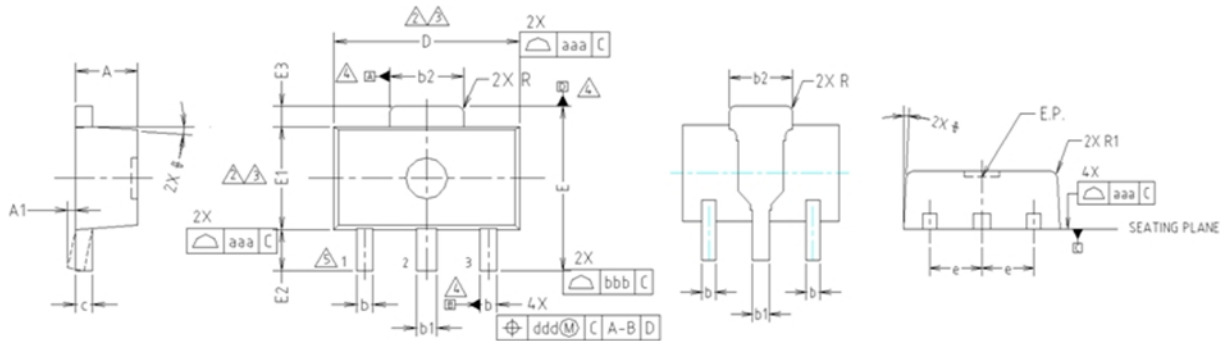


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Package Outline Dimension



NOTE:

1. DIMENSIONS IN MILLIMETERS.

⚠ DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.5mm PER END. DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.5mm PER SIDE.

⚠ DIMENSIONS D AND E1 ARE DETERMINED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.

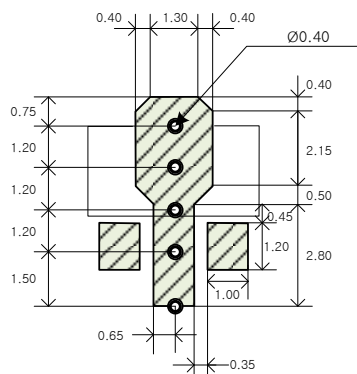
⚠ DATUMS A, B AND D TO BE DETERMINED 0.18mm FROM THE LEAD TIP.

⚠ TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

SYMBOL	MILLIMETERS			NOTE
	MINIMUM	NOMINAL	MAXIMUM	
A	1.40	1.50	1.60	
A1	0.00	—	0.10	
b	0.38	0.42	0.48	
b1	0.48	0.52	0.58	
b2	1.79	1.82	1.87	
c	0.40	0.42	0.46	
D	4.40	4.50	4.70	2,3
E	3.70	4.00	4.30	
E1	2.40	2.50	2.70	2,3
E2	0.80	1.00	1.20	
E3	0.40	0.50	0.60	
e	1.50 TYP.			
φ	4° TYP.			
R	0.15 TYP.			
R1	—	—	0.20	
SYMBOL	TOLERANCES OF FORM AND POSITION		NOTE	
aaa	0.15			
bbb	0.20			
ccc	0.10			
ddd	0.10			

Suggested PCB Land Pattern and PAD Layout

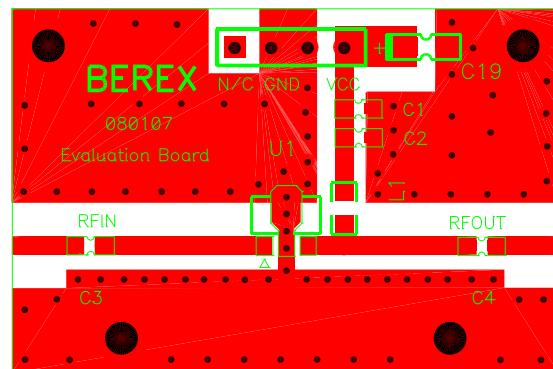
PCB Land Pattern



Note : All dimension _ millimeters

PCB lay out _ on BeRex website

PCB Mounting

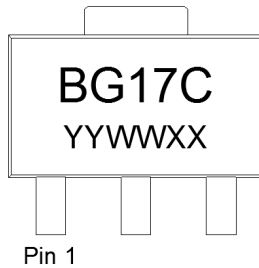


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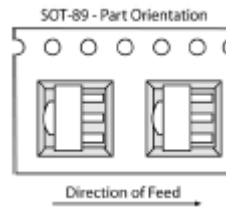
Package Marking



YY = Year, WW = Working Week,
XX = Wafer No.

Tape & Reel

SOT89



Packaging information:

Tape Width (mm): 12
Reel Size (inches): 7
Device Cavity Pitch (mm): 8
Devices Per Reel: 1000

Lead plating finish

100% Tin Matte finish

(All BeRex products undergoes a 1 hour, 150 degree C, Anneal bake to eliminate thin whisker growth concerns.)

MSL / ESD Rating

ESD Rating:	Class 2
Value:	Passes <4000V
Test:	Human Body Model (HBM)
Standard:	JEDEC Standard JESD22-A114B
MSL Rating:	Level 1 at +265°C convection reflow
Standard:	JEDEC Standard J-STD-020

NATO CAGE code:

2	N	9	6	F
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